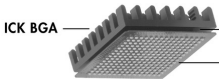




Data sheet Product ICK BGA 19 x 19 x 14



ICK BGA

WLFT 404
WLFT 405
BGA

Heatsinks and active heatsinks for processors>Heatsinks for BGAs
19 x 19 x 14 mm, for IC design BGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	19 mm
height:	14 mm
plate thickness:	1.8 mm
length:	19 mm
thermal resistance:	21 - 5 K/W
dissipation loss:	2.8 W
surface:	black anodised

Technical Drawing

